

REMARKS

Favorable reconsideration of this application, in light of the preceding amendments and following remarks, is respectfully requested.

Claims 1-14 are pending in this application. By this Amendment, claims 1-14 are amended. No new matter is added. Claim 1 is the sole independent claim.

Applicants note with appreciation the Examiner's acknowledgement that certified copies of all priority documents have been received by the U.S.P.T.O. Action, summary at 12.

Applicants also respectfully note the present action indicates that the drawings have been accepted by the Examiner. Action, summary at 10.

Applicants also note with appreciation the Examiner's consideration of the references cited in the Information Disclosure Statement filed on November 10, 2005.

Objections to Specification

The Examiner objected to the specification as it fails to contain the priority statement in the first paragraph. Applicants have amended the specification to include the priority statement. Withdrawal of the objection is respectfully requested.

Objections to the Claims

Claims 1, 3, 6, 7, and 8 stand objected to due to varying informalities. Applicants have amended claims 1, 3, 6, 7, and 8 to obviate the objections. Withdrawal of the objections is respectfully requested.

Rejections under 35 U.S.C. § 102

Claims 1-14 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent 5,598,032 to Fidalgo. Applicants respectfully traverse this rejection for the reasons discussed below.

Independent claim 1, as amended, now recites, *inter alia*:

the conductive areas of the electronic component and the conductive tracks of the substrate are in contact to achieve an electric connection via a pressure of application of the insulating material layer on the electronic component, and configured to rub together when repeated stressed are exerted on the substrate.

Applicants respectfully submit, however, that the Fidalgo reference fails to disclose, or even suggest, the subject matter presently recited in amended claim 1. In particular, the Fidalgo reference fails to disclose, or even suggest, the conductive areas of the electronic component and the conductive tracks of the substrate are in contact through a pressure of application of the insulating material layer, and configured to rub together when repeated stressed are exerted on the substrate.

As illustrated in example embodiments, the process according to Applicants' invention solves, for example, the problem of breaking an electric connection between an electronic component and conductive tracks arranged on the surface of a substrate when the latter is submitted to distortion and flexion constraints. That is, the electronic component may be made of a chip having contacts linked to conductive planar areas. The connection of these areas with conductive tracks provided on the surface of an insulating substrate may be made by the pressure exerted during gluing or laminating of an insulating film extending at least on the component and on an area of the substrate surrounding the component. Accordingly, the connection made in this

way does not need any gluing or welding rendering it rigid and breakable by flexion of the substrate.

In other words, contacting by superimposing two planar conductive surfaces (e.g., track and conductive areas) may allow sliding or rubbing of a surface when the substrate is deformed by flexion or distortion. This rubbing allows a self cleaning of the contacts without any interruption. Therefore, an advantage of the claimed invention is that the component can be placed on any position on the substrate without degradation of the quality of the connection when it is submitted to constraints.

By contrast, the Fidalgo reference discloses a method of manufacturing a contact-free hybrid card. The card includes a card body, an electronic module having an integrated circuit chip and two contact zones, and an antenna connected to the contact zones of the module by means of two contact terminals. The method may further include a step according to which a layer of the card body is negative-molded on the antenna and a cavity is made in the card body, revealing the contact terminals of the antenna, and mounting the electronic module in the cavity of the card body. For example, FIG. 5 of the Fidalgo reference discloses inserting the module into the cavity. The module is fixed to the bottom of the cavity by means of a bonder. The connections of the electrical contact is made by drops of conductive bonder (col. 5, lines 61 to col. 6 line 4).

Moreover, FIG. 7 illustrates that the contact zones of the module are connected to the terminals made of track segments on the substrate with conductive polymer, such as soldering compound or conductive bonder. (col. 6, lines 12-16).

Accordingly, such connections are rigid and do not allow a friction of both surfaces in contact when the card is deformed at the place of the electronic module. Therefore, a constraint on this type of connection leads to breaking either of the track segment on the substrate or via the gluing of the segment on the module contact. The Fidalgo reference, thus, fails to disclose, or even suggest, the feature of contacting the conductive areas of the electronic component and the conductive tracks of the substrate made by pressure and rubbing between the contact surfaces on the substrate and on the electronic component.

For at least these reasons, Applicants respectfully submit that claim 1 is allowable. Claims 2-14 are also allowable in view of their dependency on independent claim 1. Accordingly, reconsideration and withdrawal of the rejection under 35 U.S.C. § 102(b) are respectfully requested.

CONCLUSION

In view of the above remarks and amendments, the Applicants respectfully submit that each of the pending objections and rejections has been addressed and overcome, placing the present application in condition for allowance. A notice to that effect is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to contact the undersigned.

Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact the undersigned at the telephone number below.

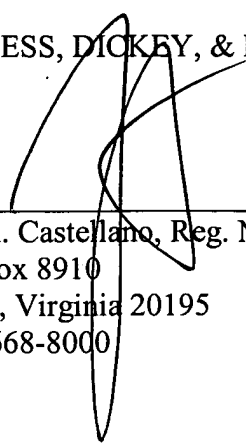
If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 08-0750 for any

additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

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By



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